Change on die passivation opening of MOSFET Source metallization

For further information, please contact your regional Vishay office.

CONTACT INFORMATION

Americas

Vishay Americas
2585 Junction Avenue
-
San Jose United States 95134- 1923
Phone: +1-408-988-8000
Fax:
-

Europe

Vishay Europe Sales GmbH
Dr Felix Zandman Platz 1
-
Selb Germany 95101
Phone: +49-9287-710
Fax:
business-europe@vishay.com

Asia

Vishay Intertechnlogy Asia Pte.Ltd
37A Tampines Street 92
#07-01
Singapore Singapore Singapore 528886
Phone: +65-6788-6668
Fax:
business-asia@vishay.com

Description of Change: The die passivation opening over the MOSFET Source metallization has been enlarged to increase the exposed solderable metal area.

Reason for Change: The passivation opening enlargement improves solder wetting and solder coverage during die attach/board assembly processes, resulting in increased process robustness and improved manufacturability.

Expected Influence on Quality/Reliability/Performance: There will be no effect on performance, quality or reliability. No impact on form, fit and function.

Part Numbers/Series/Families Affected: SIC32201CD-T1E3

Affected customers will be informed directly with a detailed part list.

Vishay Brand(S): Vishay Siliconix

Time Schedule:

Start Shipment Date: Saturday December 19, 2026

Sample Availability: Please contact your regional Vishay Sales office for sample availability.

Product Identification: Date Code

Qualification Data: Please see attached.

This PCN is considered approved, without further notification, unless we receive specific customer concerns before Saturday December 19, 2026 or as specified by contract.

Issued By: Lisette Saba, malinalisette.saba@vishay.com

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Qualification Data

October 2026

Reliability Test Results Summary

HR-CYC	S S	FAIL	DONE	TYPE	CODE	EVAL	STRESS	STEP	TEST	CONDITION
2660046	HTGB	0		HTGB (150 C)		0	84	0	X	ET
		1		HTGB (150 C)		168	84	0	X	ET
	HTRB	0		HTRB (150 C)		0	84	0	X	ET
		1		HTRB (150 C)		168	84	0	X	ET

PART NUMBER: AMSIC32201C
DATE CODE:
PURPOSE:

EVAL	STRESS	STEP	TEST CONDITION	HR-CYC	S S	FAIL	DONE	TEST TYPE	FAIL CODE
2566402	ESD - C D	0	ESD' - C D MO	0	10	0	X	ET	
		1	ESD' - C D MO	700	10	0	X	ET	
		2	ESD' - C D MO	750	10	2	X	ET	FT
	ESD - H B	0	ESD' - H B MO	0	10	0	X	ET	
		1	ESD' - H B MO	3900	10	0	X	ET	
		2	ESD' - H B MO	3950	10	2	X	ET	FT

PART NUMBER: AMSIC32201C
DATE CODE:
PURPOSE: YIELD IMPROVEMENT

EVAL	STRESS	STEP	TEST CONDITION	HR-CYC	S S	FAIL	TEST DONE	TEST TYPE	FAIL CODE
2660045	ESD - C D	0	ESD' - C D MO	0	28	0	X	ET	
		1	ESD' - C D MO	125	3	0	X	ET	
		2	ESD' - C D MO	250	3	0	X	ET	
		3	ESD' - C D MO	500	3	0	X	ET	
		4	ESD' - C D MO	750	3	0	X	ET	
		5	ESD' - C D MO	1000	3	0	X	ET	
		6	ESD' - C D MO	1500	3	0	X	ET	
		7	ESD' - C D MO	2000	10	0	X	ET	
	ESD - H B	0	ESD' - H B MO	0	21	0	X	ET	
		1	ESD' - H B MO	1000	3	0	X	ET	
		2	ESD' - H B MO	1500	3	0	X	ET	
		3	ESD' - H B MO	2000	3	0	X	ET	
		4	ESD' - H B MO	2500	3	0	X	ET	
		5	ESD' - H B MO	3000	3	0	X	ET	
		6	ESD' - H B MO	3500	3	0	X	ET	
		7	ESD' - H B MO	4000	3	0	X	ET	
	LATCH-UP	0	LATCH-UP	0	24	0	X	ET	
		1	LATCH-UP	100	6	0	X	ET	
		2	LATCH-UP	100	6	0	X	ET	
		3	LATCH-UP	150	6	0	X	ET	
		4	LATCH-UP	150	6	6	X	ET	TJ
	SS OP LIFE	0	HIGH TEMP OP	0	82	0	X	ET	
		1	HIGH TEMP OP	168	82	0	X	ET	

PART NUMBER: AMSIC32201C
DATE CODE: T542AJ
PURPOSE: